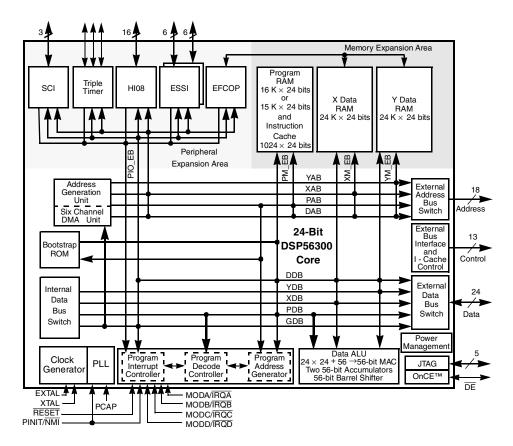
## **Freescale Semiconductor**

### **Product Brief Advance Information**

# **DSP56L307**

## 24-Bit Digital Signal Processor



The DSP56L307 is intended for applications requiring a large amount of internal memory, such as networking and wireless infrastructure applications. The EFCOP can accelerate general filtering applications, such as echo-cancellation applications, correlation, and general-purpose convolution-based algorithms.

Figure 1. DSP56L307 Block Diagram

The Freescale DSP56L307, a member of the DSP56300 DSP family, supports network applications with general filtering operations. The Enhanced Filter Coprocessor (EFCOP) executes filter algorithms in parallel with core operations, enhancing signal quality with no impact on channel throughput or total channels supported. The result is increased overall performance. Like the other DSP56300 family members, the DSP56L307 uses a high-performance, single-clock-cycle-per- instruction engine (DSP56000 code-compatible), a barrel shifter, 24-bit addressing, an instruction cache, and a direct memory access (DMA) controller (see **Figure 1**). The DSP56L307 performs at 160 million multiply-accumulates per second (MMACS), attaining 320 MMACS when the EFCOP is in use. It operates with an internal 160 MHz clock with a 1.8 volt core and independent 3.3 volt input/output (I/O) power.

Note: This document contains information on a new product. Specifications and information herein are subject to change without notice.



# **Features**

Table 1 lists the features of the DSP56L307 device.

Table 1. DSP56L307 Features

Feature	Description							
High-Performance DSP56300 Core	<ul> <li>160 million multiply-accumulates per second (MMACS) (321 MMACS using the EFCOP in filtering applications) with a 160 MHz clock at 1.8 V core and 3.3 V I/O</li> <li>Object code compatible with the DSP56000 core with highly parallel instruction set</li> <li>Data arithmetic logic unit (Data ALU) with fully pipelined 24 × 24-bit parallel multiplier-accumulator (MAC), 56-bit parallel barrel shifter (fast shift and normalization; bit stream generation and parsing), conditional ALU instructions, and 24-bit or 16-bit arithmetic support under software control</li> <li>Program control unit (PCU) with position-independent code (PIC) support, addressing modes optimized for DSP applications (including immediate offsets), internal instruction cache controller, internal memory-expandable hardware stack, nested hardware DO loops, and fast auto-return interrupts</li> <li>Direct memory access (DMA) with six DMA channels supporting internal and external accesses; one-, two-and three-dimensional transfers (including circular buffering); end-of-block-transfer interrupts; and triggering from interrupt lines and all peripherals</li> <li>Phase-lock loop (PLL) allows change of low-power divide factor (DF) without loss of lock and output clock with skew elimination</li> <li>Hardware debugging support including on-chip emulation (OnCE) module, Joint Test Action Group (JTAG) test access port (TAP)</li> </ul>							
Enhanced Filter Coprocessor (EFCOP)	<ul> <li>Internal 24 × 24-bit filtering and echo-cancellation coprocessor that runs in parallel to the DSP core</li> <li>Operation at the same frequency as the core (up to 160 MHz)</li> <li>Support for a variety of filter modes, some of which are optimized for cellular base station applications:</li> <li>Real finite impulse response (FIR) with real taps</li> <li>Complex FIR with complex taps</li> <li>Complex FIR generating pure real or pure imaginary outputs alternately</li> <li>A 4-bit decimation factor in FIR filters, thus providing a decimation ratio up to 16</li> <li>Direct form 1 (DFI) Infinite Impulse Response (IIR) filter</li> <li>Direct form 2 (DFII) IIR filter</li> <li>Four scaling factors (1, 4, 8, 16) for IIR output</li> <li>Adaptive FIR filter with true least mean square (LMS) coefficient updates</li> <li>Adaptive FIR filter with delayed LMS coefficient updates</li> </ul>							
Internal Peripherals	<ul> <li>Enhanced 8-bit parallel host interface (HI08) supports a variety of buses (for example, ISA) and provides glueless connection to a number of industry-standard microcomputers, microprocessors, and DSPs</li> <li>Two enhanced synchronous serial interfaces (ESSI), each with one receiver and three transmitters (allows six-channel home theater)</li> <li>Serial communications interface (SCI) with baud rate generator</li> <li>Triple timer module</li> <li>Up to 34 programmable general-purpose input/output (GPIO) pins, depending on which peripherals are enabled</li> </ul>							
	192 × 24-bit bootstrap ROM     192 K × 24-bit RAM total     Program RAM, instruction cache, X data RAM, and Y data RAM sizes are programmable:							
	Program RAM Size	Instruction Cache Size	X Data RAM Size*	Y Data RAM Size*	Instruction Cache	Switch Mode	MSW1	MSW0
	16 K × 24-bit	0	24 K × 24-bit	24 K × 24-bit	disabled	disabled	0/1	0/1
	15 K × 24-bit	1024 × 24-bit	24 K × 24-bit	24 K × 24-bit	enabled	disabled	0/1	0/1
	48 K × 24-bit	0	8 K × 24-bit	8 K × 24-bit	disabled	enabled	0	0
Internal Memories	47 K × 24-bit	1024 × 24-bit	8 K × 24-bit	8 K × 24-bit	enabled	enabled	0	0
	40 K × 24-bit	0	12 K × 24-bit	12 K × 24-bit	disabled	enabled	0	1
	39 K × 24-bit	1024 × 24-bit	12 K × 24-bit	12 K × 24-bit	enabled	enabled	0	1
	32 K × 24-bit	0	16 K × 24-bit	16 K × 24-bit	disabled	enabled	1	0
	31 K × 24-bit	1024 × 24-bit	16 K × 24-bit	16 K × 24-bit	enabled	enabled	1	0
	24 K × 24-bit	0	20 K × 24-bit	20 K × 24-bit	disabled	enabled	1	1
	23 K × 24-bit	1024 × 24-bit	20 K × 24-bit	20 K × 24-bit	enabled	enabled	1	1
	*Includes 4 K × 24-bit shared memory (that is, memory shared by the core and the EFCOP)							

DSP56L307 Product Brief, Rev. 2

2 Freescale Semiconductor

Table 1. DSP56L307 Features (Continued)

Feature	Description				
External Memory Expansion	<ul> <li>Data memory expansion to two 256 K × 24-bit word memory spaces using the standard external address lines</li> <li>Program memory expansion to one 256 K × 24-bit words memory space using the standard external address lines</li> <li>External memory expansion port</li> <li>Chip select logic for glueless interface to static random access memory (SRAMs)</li> <li>Internal DRAM Controller for glueless interface to dynamic random access memory (DRAMs) up to 100 MHz operating frequency</li> </ul>				
Power Dissipation	Very low-power CMOS design     Wait and Stop low-power standby modes     Fully static design specified to operate down to 0 Hz (dc)     Optimized power management circuitry (instruction-dependent, peripheral-dependent, and modedependent)				
Packaging	Molded array plastic-ball grid array (MAP-BGA) package in lead-free or lead-bearing versions.				

# **Target Applications**

- Wireless and wireline infrastructure applications
- Multi-channel wireless local loop systems
- DSP resource boards
- High-speed modem banks
- Packet telephony

## **Product Documentation**

The documents listed in **Table 2** are required for a complete description of the DSP56L307 device and are necessary to design properly with the part. Documentation is available from a local Freescale distributor, a Freescale semiconductor sales office, or a Freescale Semiconductor Literature Distribution Center. For documentation updates, visit the Freescale DSP website. See the contact information on the back cover of this document.

Table 2. DSP56L307 Documentation

Name	Description	Order Number		
DSP56L307 Technical Data	Description, features list, and specifications of the DSP56L307	DSP56L307		
DSP56L307 User's Manual	Detailed functional description of the DSP56L307 memory configuration, operation, and register programming	DSP56L307UM		
DSP56300 Family Manual	Detailed description of the DSP56300 family processor core and instruction set	DSP56300FM		
Application Notes	Documents describing specific applications or optimized device operation including code examples	See the DSP56L307 product website		

Freescale Semiconductor 3

#### How to Reach Us:

#### Home Page:

www.freescale.com

support@freescale.com

#### **USA/Europe or Locations not listed:**

Freescale Semiconductor Technical Information Center, CH370 1300 N. Alma School Road Chandler, Arizona 85224 +1-800-521-6274 or +1-480-768-2130 support@freescale.com

### Europe, Middle East, and Africa:

Freescale Halbleiter Deutschland GMBH Technical Information Center Schatzbogen 7 81829 München, Germany +44 1296 380 456 (English) +46 8 52200080 (English) +49 89 92103 559 (German) +33 1 69 35 48 48 (French) support@freescale.com

#### Japan:

Freescale Semiconductor Japan Ltd. Headquarters ARCO Tower 15F 1-8-1, Shimo-Meguro, Meguro-ku, Tokyo 153-0064, Japan 0120 191014 or +81 3 5437 9125 support.japan@freescale.com

#### Asia/Pacific:

Freescale Semiconductor Hong Kong Ltd. **Technical Information Center** 2 Dai King Street Tai Po Industrial Estate Tai Po, N.T. Hong Kong +800 2666 8080 support.asia@freescale.com

For Literature Requests Only: Freescale Semiconductor Literature Distribution Center P.O. Box 5405 Denver, Colorado 80217 1-800-441-2447 or 303-675-2140 Fax: 303-675-2150  $LDCF or Free scale Semiconductor @\,hibbert group.com$ 

DSP56L307PB Rev. 2 1/2005

Information in this document is provided solely to enable system and software implementers to use Freescale Semiconductor products. There are no express or implied copyright licenses granted hereunder to design or fabricate any integrated circuits or integrated circuits based on the information in this document.

Freescale Semiconductor reserves the right to make changes without further notice to any products herein. Freescale Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Freescale Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters which may be provided in Freescale Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. Freescale Semiconductor does not convey any license under its patent rights nor the rights of others. Freescale Semiconductor products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Freescale Semiconductor product could create a situation where personal injury or death may occur. Should Buyer purchase or use Freescale Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold Freescale Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Freescale Semiconductor was negligent regarding the design or manufacture of the part.

Freescale™ and the Freescale logo are trademarks of Freescale Semiconductor, Inc. All other product or service names are the property of their respective owners.

© Freescale Semiconductor, Inc. 2001, 2005.

